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10/2005—Rev. 0 to Rev. A

Added AD8619 ... Universal
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9/2005—Revision 0: Initial Version

SPECIFICATIONS

Electrical characteristics at V_{SY} = 5 V, V_{CM} = V_{SY}/2, T_A = 25°C, unless otherwise noted.

Table 1.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Offset Voltage	V_{OS}	−0.3 V < V_{CM} < +5.3 V		0.4	2.2	mV
		−40°C < T_A < +125°C, −0.3 V < V_{CM} < +5.2 V			2.2	mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	−40°C < T_A < +125°C		1	4.5	µV/°C
AD8613				2.5	7.0	µV/°C
Input Bias Current	I_B			0.2	1	pA
		−40°C < T_A < +85°C			110	pA
		−40°C < T_A < +125°C			780	pA
Input Offset Current	I_{OS}			0.1	0.5	pA
		−40°C < T_A < +85°C			50	pA
		−40°C < T_A < +125°C			250	pA
Input Voltage Range	IVR		0		5	V
Common-Mode Rejection Ratio	CMRR	0 V < V_{CM} < 5 V		95		dB
		−40°C < T_A < +125°C	68			dB
Large Signal Voltage Gain	A_{VO}	R_L = 10 kΩ, 0.5 V < V_O < 4.5 V	235	500		V/mV
Input Capacitance	C_{DIFF}			1.9		pF
	C_{CM}			2.5		pF
OUTPUT CHARACTERISTICS						
Output Voltage High	V_{OH}	I_L = 1 mA	4.95	4.98		V
		−40°C to +125°C	4.9			V
		I_L = 10 mA		4.7		V
		−40°C to +125°C	4.50			V
Output Voltage Low	V_{OL}	I_L = 1 mA		20	30	mV
		−40°C to +125°C			50	mV
		I_L = 10 mA		190	275	mV
		−40°C to +125°C			335	mV
Short-Circuit Current	I_{SC}			±80		mA
Closed-Loop Output Impedance	Z_{OUT}	f = 10 kHz, A_V = 1		15		Ω
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	1.8 V < V_{SY} < 5 V	67	94		dB
		−40°C < T_A < +125°C	64			dB
Supply Current/Amplifier	I_{SY}	V_O = V_{SY}/2		38		µA
		−40°C <T_A < +125°C			50	µA
DYNAMIC PERFORMANCE						
Slew Rate	SR	R_L = 10 kΩ		0.1		V/µs
Settling Time to 0.1%	t_S	G = ±1, V_{IN} = 2 V step, C_L = 20 pF, R_L = 1 kΩ		23		µs
Gain Bandwidth Product	GBP	R_L = 100 kΩ		400		kHz
		R_L = 10 kΩ		350		kHz
Phase Margin	$Ø_M$	R_L = 10 kΩ, R_L = 100 kΩ, C_L = 20 pF		70		Degrees
NOISE PERFORMANCE						
Peak-to-Peak Noise	e_n p-p	0.1 Hz to 10 Hz		2.3	3.5	µV
Voltage Noise Density	e_n	f = 1 kHz		25		nV/√Hz
		f = 10 kHz		22		nV/√Hz
Current Noise Density	i_n	f = 1 kHz		0.05		pA/√Hz

Electrical characteristics at V_{SY} = 1.8 V, V_{CM} = V_{SY}/2, T_A = 25°C, unless otherwise noted.

Table 2.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Offset Voltage	V_{OS}	−0.3 V < V_{CM} < +1.9 V		0.4	2.2	mV
		−0.3 V < V_{CM} < +1.8 V; −40°C < T_A < +125°C			2.2	mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	−40°C < T_A < +125°C		1	8.5	µV/°C
AD8613				3.7	9.0	µV/°C
Input Bias Current	I_B			0.2	1	pA
		−40°C < T_A < +85°C			110	pA
		−40°C < T_A < +125°C			780	pA
Input Offset Current	I_{OS}			0.1	0.5	pA
		−40°C < T_A < +85°C			50	pA
		−40°C < T_A < +125°C			250	pA
Input Voltage Range	IVR		0		1.8	V
Common-Mode Rejection Ratio	CMRR	0 V < V_{CM} < 1.8 V	58	86		dB
		−40°C < T_A < +125°C	55			dB
Large Signal Voltage Gain	A_{VO}	R_L = 10 kΩ, 0.5 V < V_O < 1.3 V	85	1000		V/mV
Input Capacitance	C_{DIFF}			2.1		pF
	C_{CM}			3.8		pF
OUTPUT CHARACTERISTICS						
Output Voltage High	V_{OH}	I_L = 1 mA	1.65	1.73		V
		−40°C to +125°C	1.6			V
Output Voltage Low	V_{OL}	I_L = 1 mA		44	60	mV
		−40°C to +125°C			80	mV
Short-Circuit Current	I_{SC}			±7		mA
Closed-Loop Output Impedance	Z_{OUT}	f = 10 kHz, A_V = 1		15		Ω
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	1.8 V < V_S < 5 V	67	94		dB
Supply Current/Amplifier	I_{SY}	V_O = V_{SY}/2		38		µA
		−40°C <T_A < +125°C			50	µA
DYNAMIC PERFORMANCE						
Slew Rate	SR	R_L = 10 kΩ		0.1		V/µs
Settling Time to 0.1%	t_S	G = ±1, V_{IN} = 1 V step, C_L = 20 pF, R_L = 1 kΩ		6.5		µs
Gain Bandwidth Product	GBP	R_L = 100 kΩ		400		kHz
		R_L = 10 kΩ		350		kHz
Phase Margin	$Ø_M$	R_L = 10 kΩ, R_L = 100 kΩ, C_L = 20 pF		70		Degrees
NOISE PERFORMANCE						
Peak-to-Peak Noise	e_n p-p	0.1 Hz to 10 Hz		2.3	3.5	µV
Voltage Noise Density	e_n	f = 1 kHz		25		nV/√Hz
		f = 10 kHz		22		nV/√Hz
Current Noise Density	i_n	f = 1 kHz		0.05		pA/√Hz

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C, unless otherwise noted.

Table 3.

Parameter	Rating
Supply Voltage	6 V
Input Voltage	V_{SS} − 0.3 V to V_{DD} + 0.3 V
Input Current	±10 mA
Differential Input Voltage	±6 V
Output Short-Circuit Duration to GND	Indefinite
Storage Temperature Range	−65°C to +150°C
Operating Temperature Range	−40°C to +125°C
Junction Temperature Range	−65°C to +150°C
Lead Temperature (Soldering, 60 sec)	300°C
ESD AD8613	
HBM	±4000 V
FICDM	±1000 V
ESD AD8617	
HBM	±3000 V
FICDM	±1000 V
MM	±100 V
ESD AD8619	
HBM	±4000 V
FICDM	±1250 V
MM	±200 V

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

θ_{JA} is specified for the worst-case conditions, that is, a device soldered in a circuit board for surface-mount packages.

Table 4. Thermal Characteristics

Package Type	θ_{JA}	θ_{JC}	Unit
5-Lead TSOT-23 (UJ-5)	207	61	°C/W
5-Lead SC70 (KS-5)	376	126	°C/W
8-Lead MSOP (RM-8)	210	45	°C/W
8-Lead SOIC_N (R-8)	158	43	°C/W
8-Lead LFCSP (CP-8-21)	81	20	°C/W
14-Lead SOIC_N (R-14)	120	36	°C/W
14-Lead TSSOP (RU-14)	180	35	°C/W

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

TYPICAL PERFORMANCE CHARACTERISTICS

V_{SY} = 5 V or ±2.5 V, unless otherwise noted.

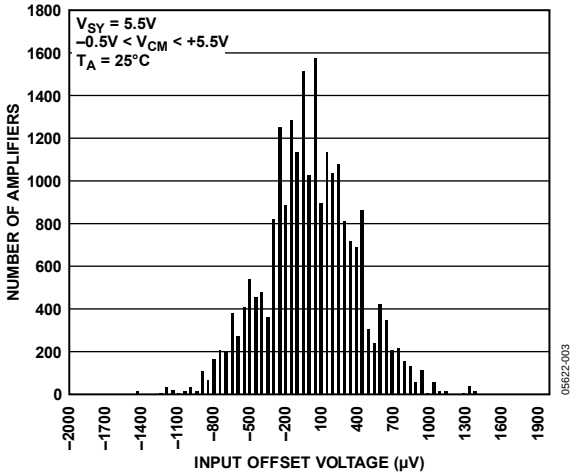


Figure 5. Input Offset Voltage Distribution

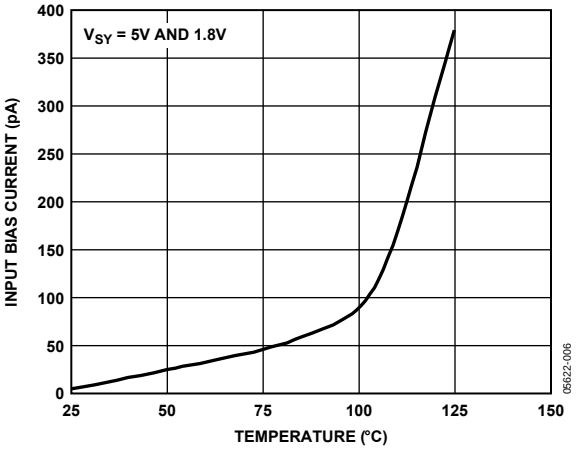


Figure 8. Input Bias Current vs. Temperature

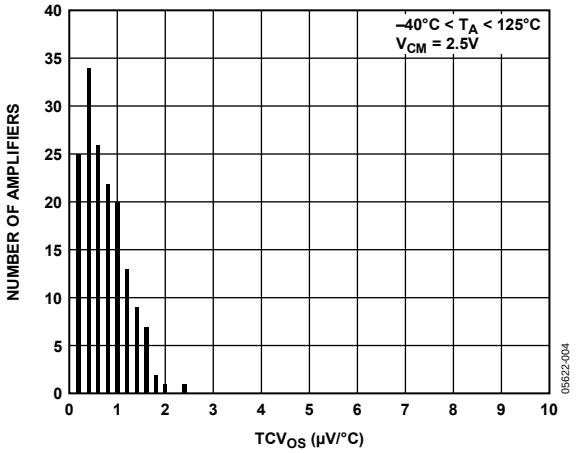


Figure 6. Input Offset Voltage Drift Distribution

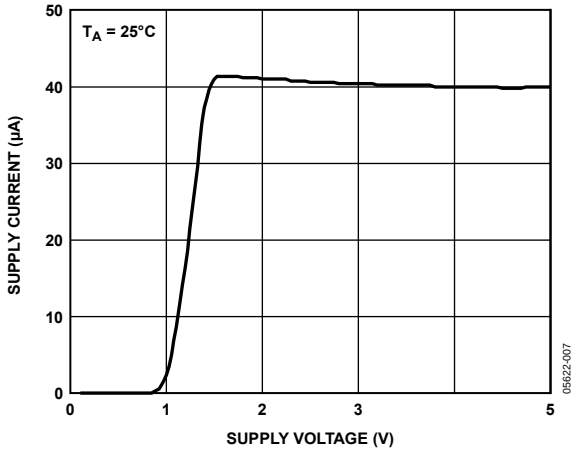


Figure 9. Supply Current vs. Supply Voltage

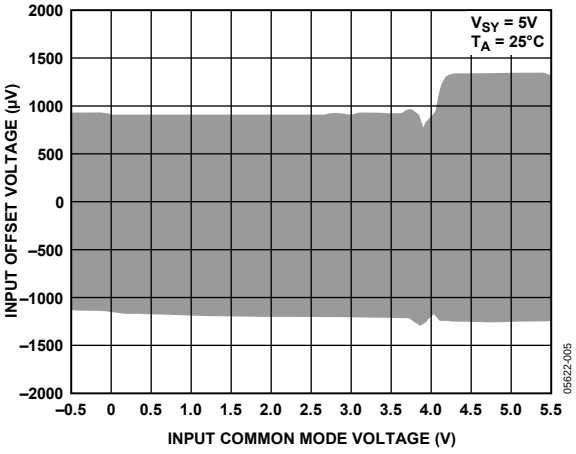


Figure 7. Input Offset Voltage vs. Input Common-Mode Voltage

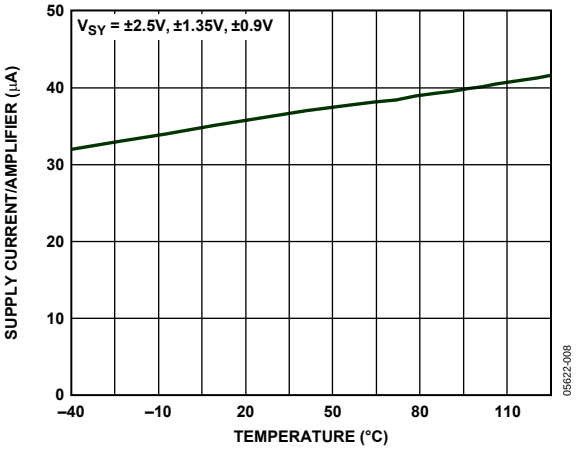


Figure 10. Supply Current vs. Temperature

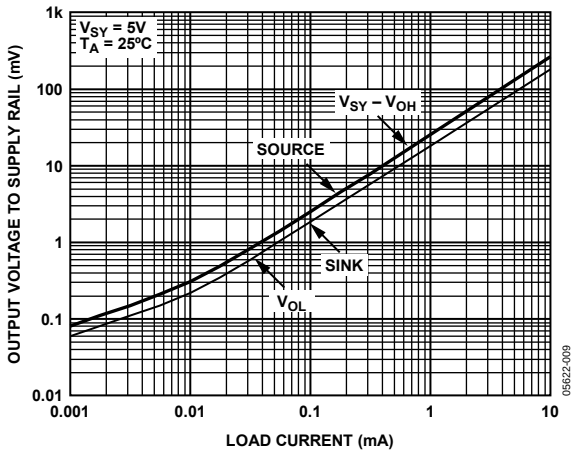


Figure 11. Output Voltage to Supply Rail vs. Load Current

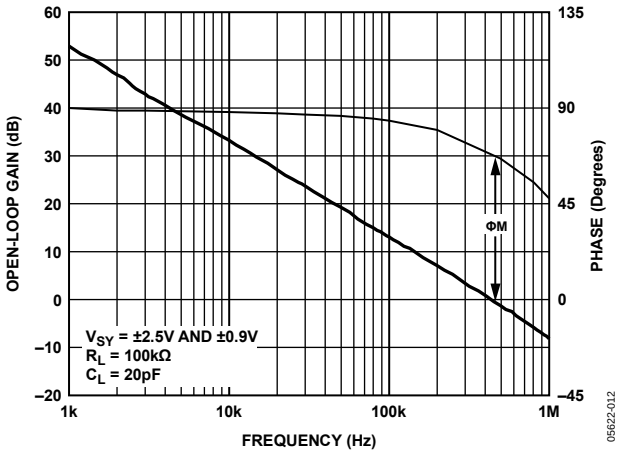


Figure 14. Open-Loop Gain and Phase vs. Frequency

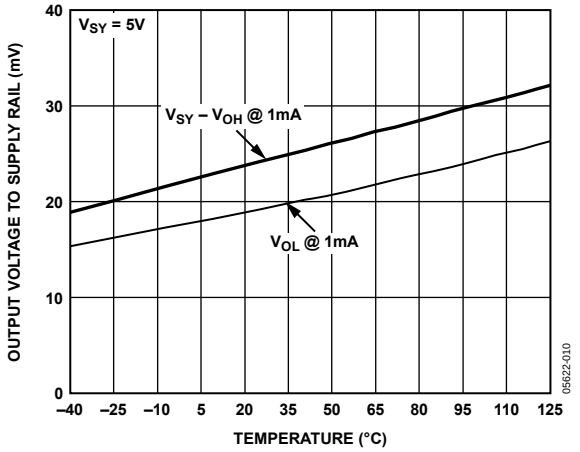


Figure 12. Output Voltage to Supply Rail vs. Temperature (I_L = 1 mA)

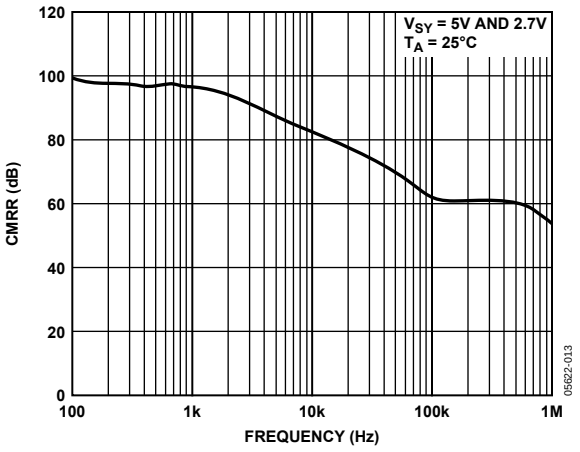


Figure 15. CMRR vs. Frequency

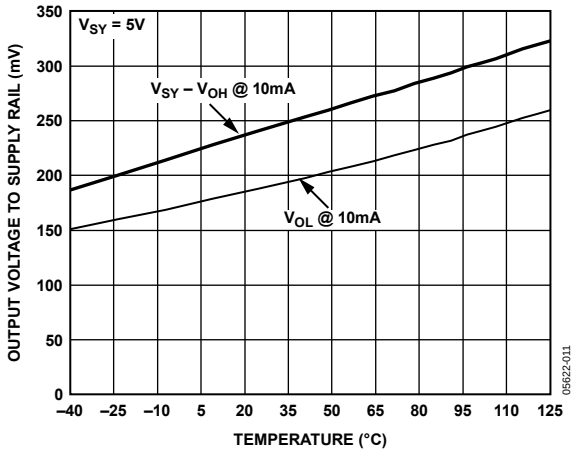


Figure 13. Output Voltage to Supply Rail vs. Temperature (I_L = 10 mA)

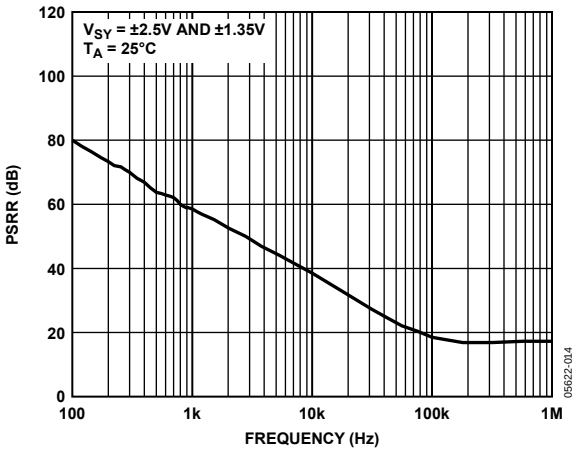


Figure 16. PSRR vs. Frequency

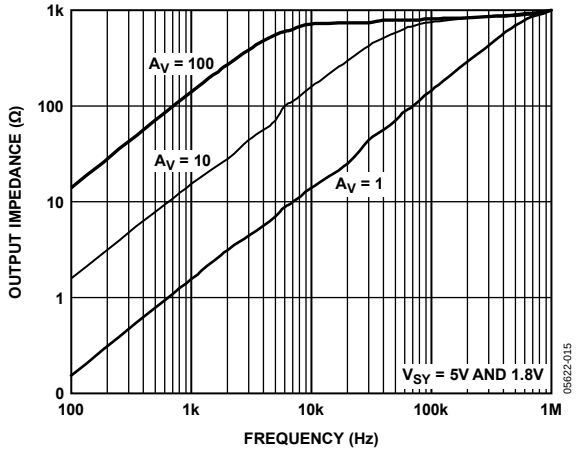


Figure 17. Output Impedance vs. Frequency

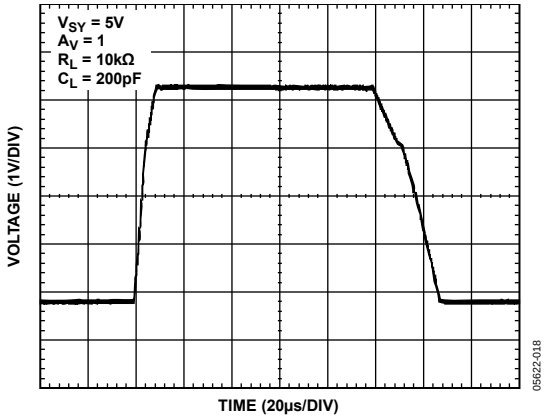


Figure 20. Large Signal Transient Response

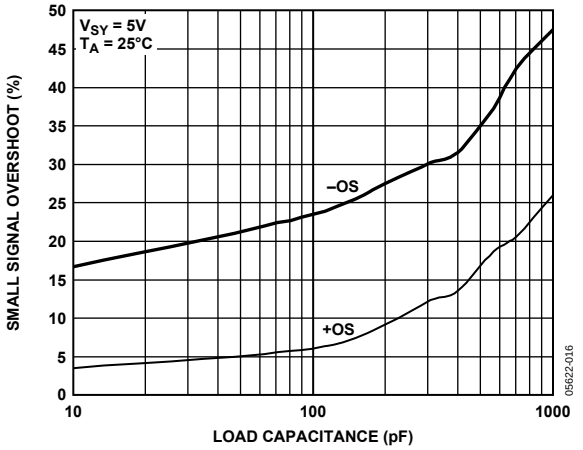


Figure 18. Small Signal Overshoot vs. Load Capacitance

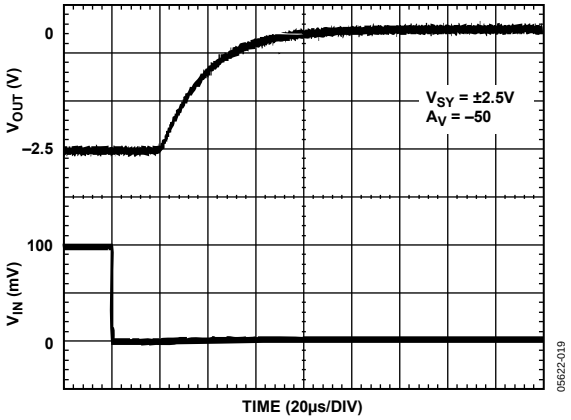


Figure 21. Positive Overload Recovery

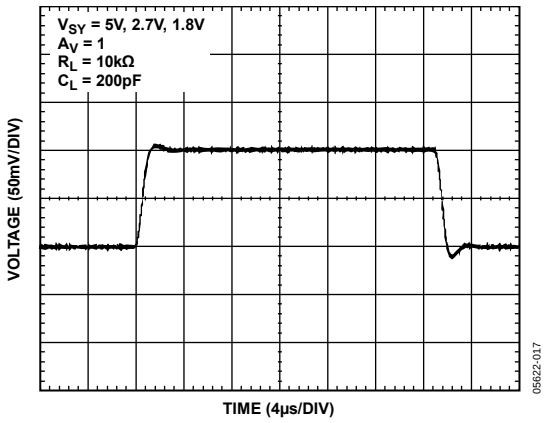


Figure 19. Small Signal Transient Response

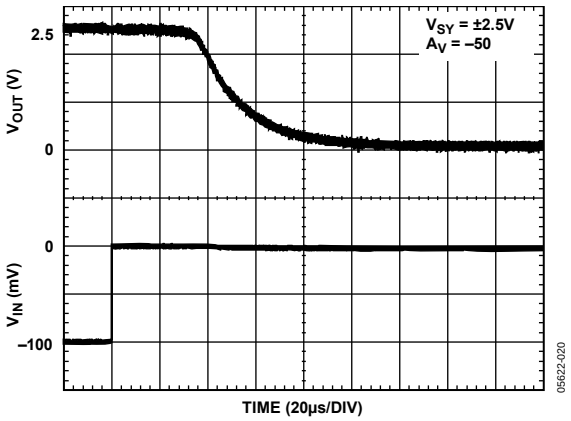


Figure 22. Negative Overload Recovery

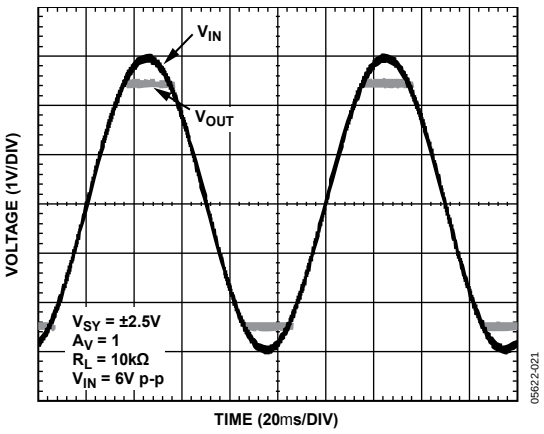


Figure 23. No Phase Reversal

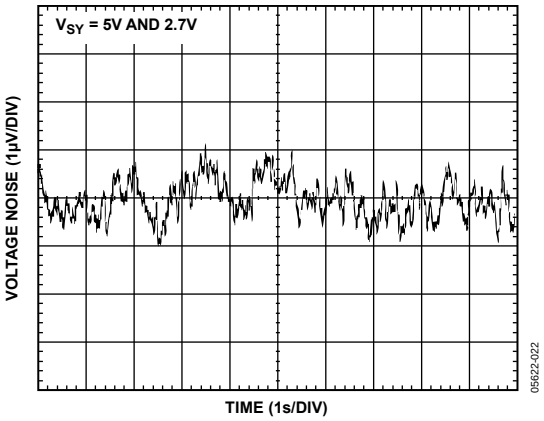


Figure 24. 0.1 Hz to 10 Hz Input Voltage Noise

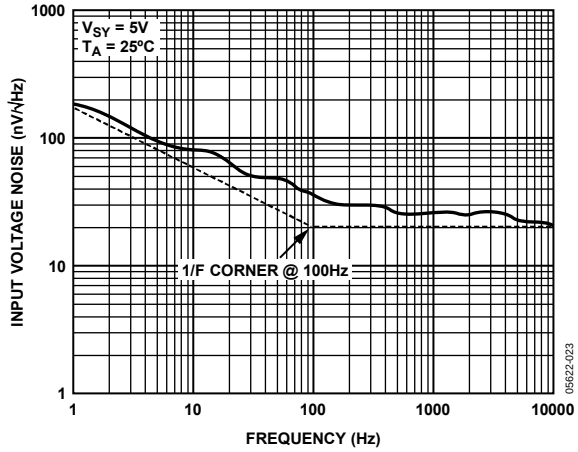


Figure 25. Voltage Noise Density

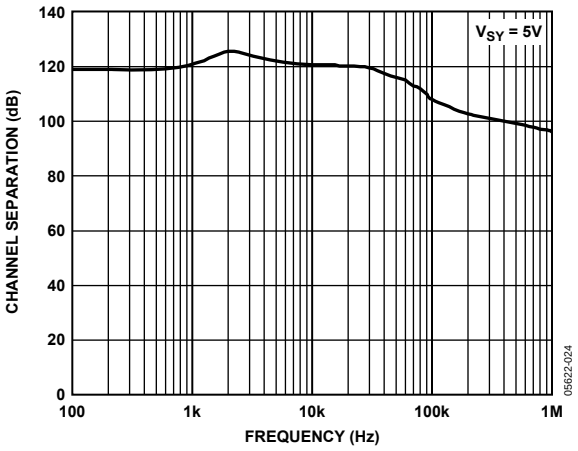


Figure 26. Channel Separation

V_{SY} = 1.8 V or ±0.9 V, unless otherwise noted.

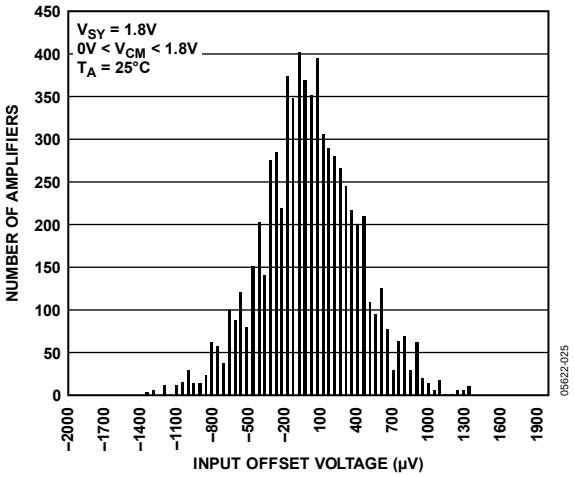


Figure 27. Input Offset Voltage Distribution

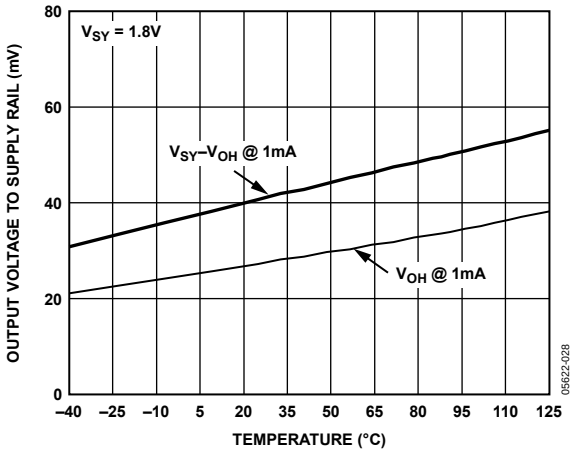


Figure 30. Output Voltage to Supply Rail vs. Temperature (I_L = 1 mA)

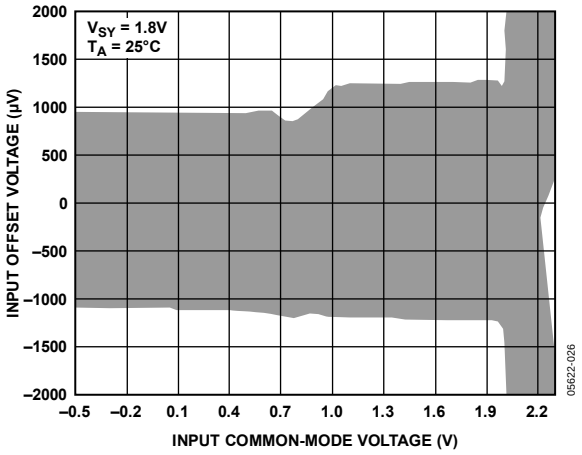


Figure 28. Input Offset Voltage vs. Input Common-Mode Voltage

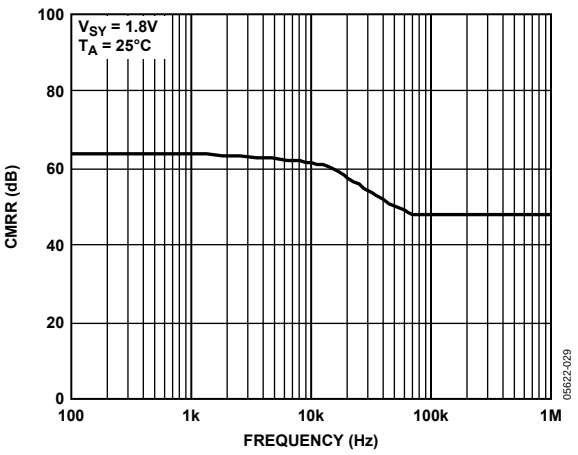


Figure 31. CMRR vs. Frequency

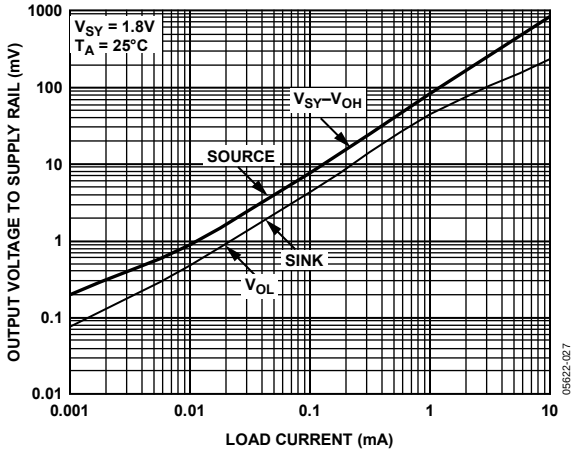


Figure 29. Output Voltage to Supply Rail vs. Load Current

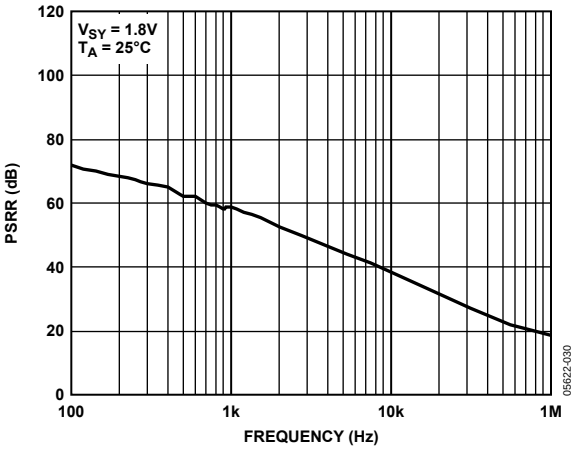


Figure 32. PSRR vs. Frequency

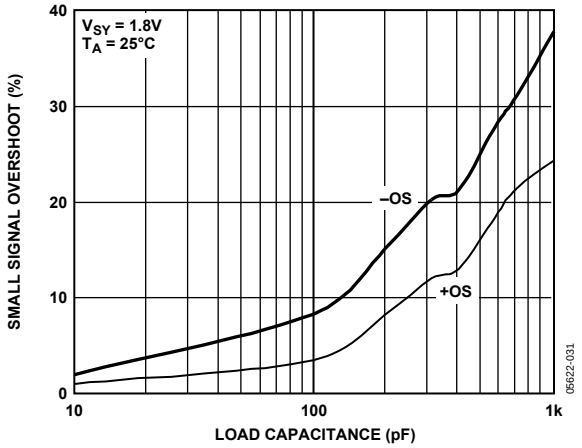


Figure 33. Small Signal Overshoot vs. Load Capacitance

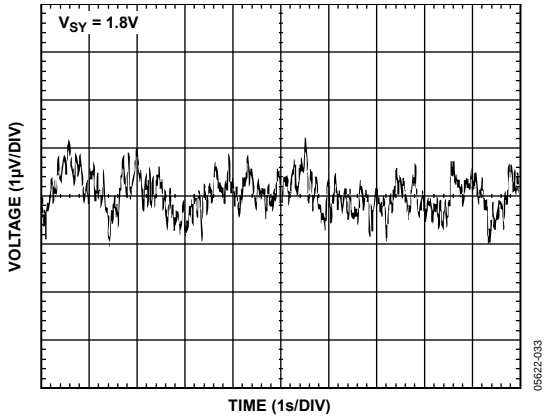


Figure 35. 0.1 Hz to 10 Hz Input Voltage Noise

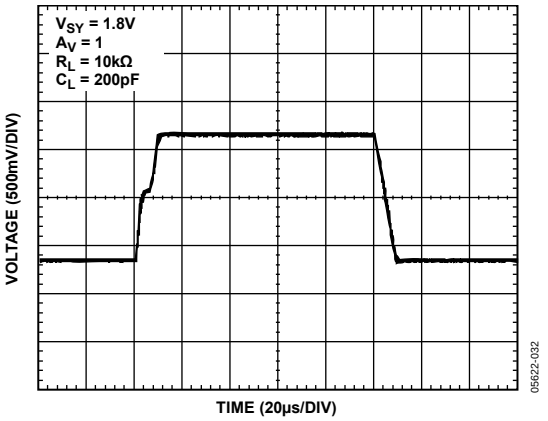


Figure 34. Large Signal Transient Response

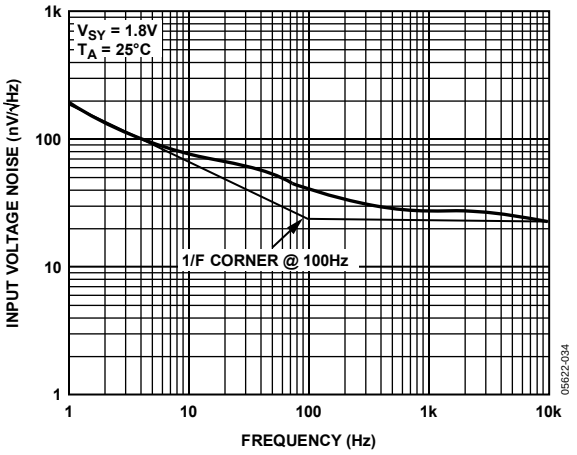
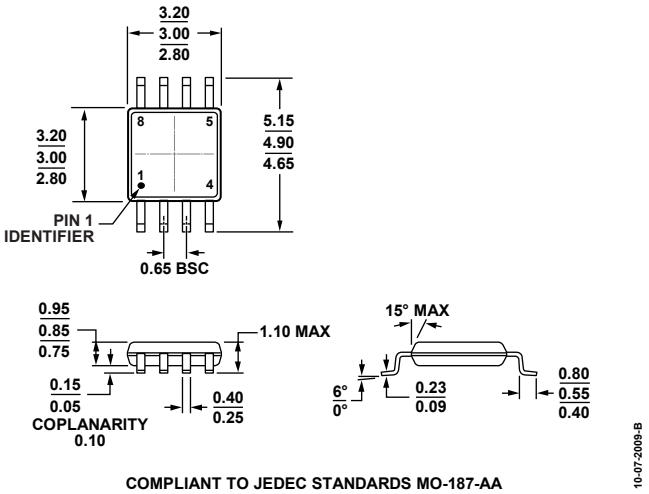


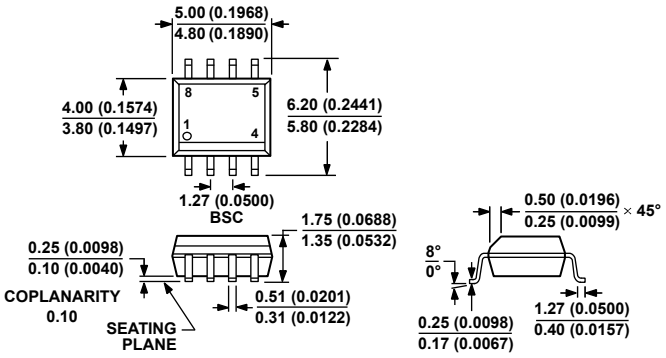
Figure 36. Voltage Noise Density

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-187-AA

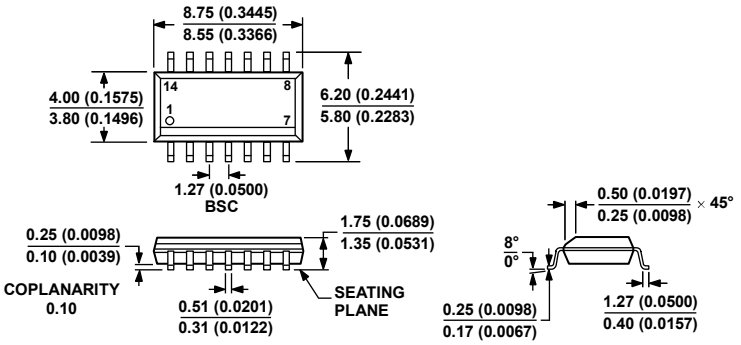
Figure 37. 8-Lead Mini Small Outline Package [MSOP]
(RM-8)
Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MS-012-AA

CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

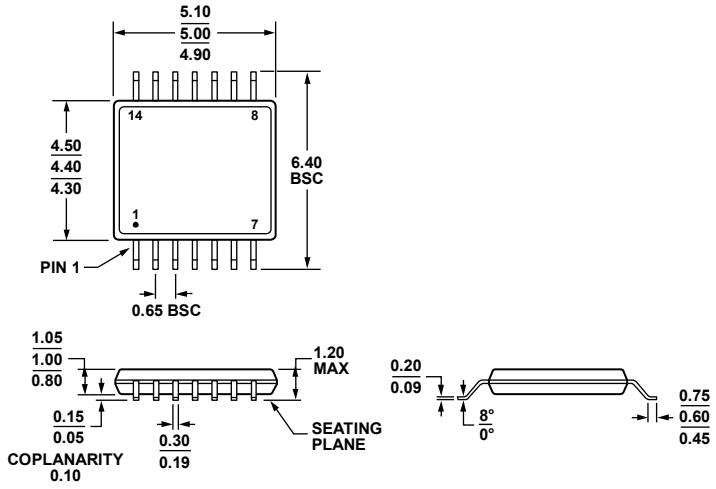
Figure 38. 8-Lead Standard Small Outline Package [SOIC_N]
Narrow Body (R-8)
Dimensions shown in millimeters and (inches)



COMPLIANT TO JEDEC STANDARDS MS-012-AB
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

060606-A

Figure 39. 14-Lead Standard Small Outline Package [SOIC_N]
Narrow Body (R-14)
Dimensions shown in millimeters and (inches)



COMPLIANT TO JEDEC STANDARDS MO-153-AB-1

061908-A

Figure 40. 14-Lead Thin Shrink Small Outline Package [TSSOP]
(RU-14)
Dimensions shown in millimeters

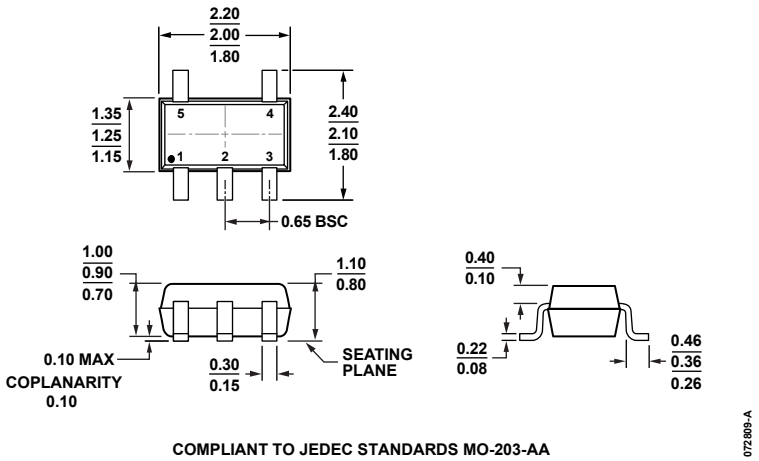


Figure 41. 5-Lead Thin Shrink Small Outline Transistor Package [SC70]
(KS-5)
Dimensions shown in millimeters

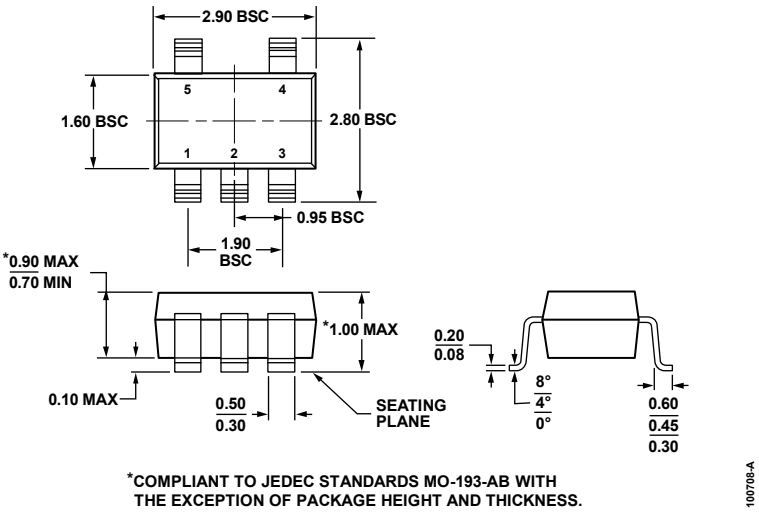


Figure 42. 5-Lead Thin Small Outline Transistor Package [TSOT-23]
(UJ-5)
Dimensions shown in millimeters

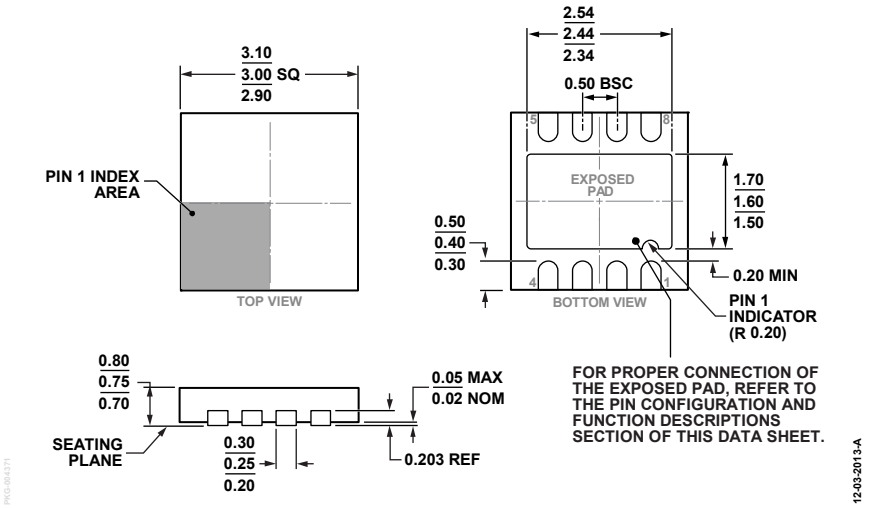


Figure 43. 8-Lead Lead Frame Chip Scale Package [LFCSP]
3 mm × 3 mm Body and 0.75 mm Package Height
(CP-8-21)
Dimensions shown in millimeters

ORDERING GUIDE

Model[1, 2]	Temperature Range	Package Description	Package Option	Branding
AD8613AKSZ-R2	−40°C to +125°C	5-Lead SC70	KS-5	A0Y
AD8613AKSZ-REEL	−40°C to +125°C	5-Lead SC70	KS-5	A0Y
AD8613AKSZ-REEL7	−40°C to +125°C	5-Lead SC70	KS-5	A0Y
AD8613AUJZ-R2	−40°C to +125°C	5-Lead TSOT-23	UJ-5	A0Y
AD8613AUJZ-REEL	−40°C to +125°C	5-Lead TSOT-23	UJ-5	A0Y
AD8613AUJZ-REEL7	−40°C to +125°C	5-Lead TSOT-23	UJ-5	A0Y
AD8617ACPZ-R2	−40°C to +125°C	8-Lead LFCSP	CP-8-21	A0T
AD8617ACPZ-R7	−40°C to +125°C	8-Lead LFCSP	CP-8-21	A0T
AD8617ARMZ	−40°C to +125°C	8-Lead MSOP	RM-8	A0T
AD8617ARMZ-REEL	−40°C to +125°C	8-Lead MSOP	RM-8	A0T
AD8617ARZ	−40°C to +125°C	8-Lead SOIC_N	R-8	
AD8617ARZ-REEL	−40°C to +125°C	8-Lead SOIC_N	R-8	
AD8617ARZ-REEL7	−40°C to +125°C	8-Lead SOIC_N	R-8	
AD8617WARMZ-REEL	−40°C to +125°C	8-Lead MSOP	RM-8	A23
AD8617WARZ-RL	−40°C to +125°C	8-Lead SOIC_N	R-8	
AD8617WARZ-R7	−40°C to +125°C	8-Lead SOIC_N	R-8	
AD8619ARUZ	−40°C to +125°C	14-Lead TSSOP	RU-14	
AD8619ARUZ-REEL	−40°C to +125°C	14-Lead TSSOP	RU-14	
AD8619ARZ	−40°C to +125°C	14-Lead SOIC_N	R-14	
AD8619ARZ-REEL7	−40°C to +125°C	14-Lead SOIC_N	R-14	
AD8619WARZ-RL	−40°C to +125°C	14-Lead SOIC_N	R-14	
AD8619WARZ-R7	−40°C to +125°C	14-Lead SOIC_N	R-14	
AD8619WARUZ-R7	−40°C to +125°C	14-Lead TSSOP	RU-14	
AD8619WARUZ-RL	−40°C to +125°C	14-Lead TSSOP	RU-14	

[1] Z = RoHS Compliant Part.
[2] W = Qualified for Automotive Applications.

AUTOMOTIVE PRODUCTS

The AD8617W and AD8619W models are available with controlled manufacturing to support the quality and reliability requirements of automotive applications. Note that these automotive models may have specifications that differ from the commercial models; therefore, designers should review the Specifications section of this data sheet carefully. Only the automotive grade products shown are available for use in automotive applications. Contact your local Analog Devices account representative for specific product ordering information and to obtain the specific Automotive Reliability reports for these models.